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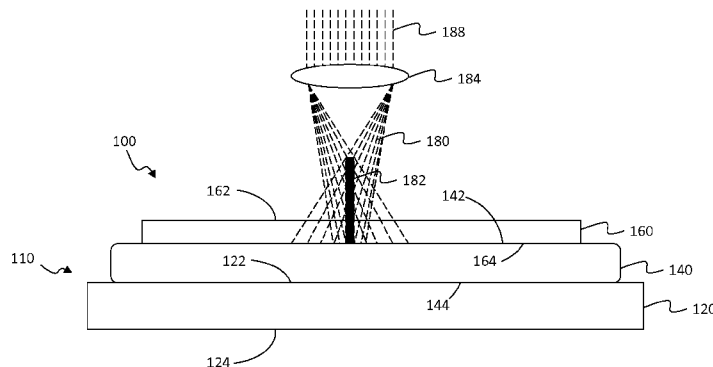


FIG. 1

(57) Abstract: Methods of laser processing a transparent material are disclosed. The method may include positioning the transparent material on a carrier and transmitting a laser beam through the transparent material, where the laser beam may be incident on a side of the transparent material opposite the carrier. The transparent material may be substantially transparent to the laser beam and the carrier may include a support base and a laser disruption element. The laser disruption element may disrupt the laser beam transmitted through the transparent material such that the laser beam may not have sufficient intensity below the laser disruption element to damage the support base.

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## METHODS AND APPARATUSES FOR LASER PROCESSING MATERIALS

### RELATED APPLICATIONS

This application claims the benefit of U.S. Provisional Application No. 62/021917, filed on July 08, 2014. The entire teachings of the above applications are incorporated herein by reference.

### TECHNICAL FIELD

**[0001]** The present specification relates generally to the manufacture of materials and, more specifically, to laser processing of materials.

### BACKGROUND

**[0002]** In recent years, customer demand to reduce the size, weight, and material cost of devices has led to considerable technological growth in flat panel displays for touch screens, tablets, smartphones, and TVs. Industrial lasers are becoming important tools for applications requiring high precision cutting of these materials. However, laser processing can be difficult because the high intensity laser may damage the components utilized in laser processing of the materials.

**[0003]** Accordingly, a need exists for alternative methods and apparatuses for laser processing materials.

### SUMMARY

**[0004]** The embodiments described herein relate to methods and apparatuses for laser processing materials. According to one embodiment, transparent material may be laser processed. The method may comprise positioning the transparent material on a carrier and transmitting a laser beam through the transparent material, where the laser beam may be incident on a side of the transparent material opposite the carrier. The transparent material may be substantially transparent to the laser beam and the carrier may comprise a support base and a laser disruption element. The laser disruption element may disrupt the laser beam transmitted

through the transparent material such that the laser beam may not have sufficient intensity below the laser disruption element to damage the support base.

**[0005]** In another embodiment, a multilayer stack for laser processing may comprise a carrier comprising a support base and a laser disruption element, and a transparent material positioned on the carrier. The laser disruption element may be positioned on top of the support base. The transparent material may comprise a substantially flat top surface and a substantially flat bottom surface, wherein the transparent material may be substantially transparent to a laser beam incident on a surface of the transparent material opposite the carrier. The laser disruption element may optically disrupt the laser beam transmitted through the transparent material such that the laser beam may not have sufficient intensity below the laser disruption element to damage the support base.

**[0006]** In yet another embodiment, a carrier may be protected when a transparent material positioned on the carrier is laser processed. The method may comprise positioning the transparent material on top of the carrier, transmitting a laser beam through the transparent material, and positioning a laser disruption element between the support base and the transparent material. The carrier may comprise a support base. The laser beam may be incident on a surface of the transparent material opposite the carrier and the laser beam may comprise a focal area having an intensity sufficient to damage the carrier. The laser disruption element may optically disrupt the laser beam transmitted through the transparent material such that the laser beam may not have sufficient intensity at any point below the laser disruption element to damage the support base.

**[0007]** Additional features and advantages of the embodiments described herein will be set forth in the detailed description which follows, and in part will be readily apparent to those skilled in the art from that description or recognized by practicing the embodiments described herein, including the detailed description which follows, the claims, as well as the appended drawings.

**[0008]** It is to be understood that both the foregoing general description and the following detailed description describe various embodiments and are intended to provide an overview or framework for understanding the nature and character of the claimed subject matter. The accompanying drawings are included to provide a further understanding of the various

embodiments, and are incorporated into and constitute a part of this specification. The drawings illustrate the various embodiments described herein, and together with the description serve to explain the principles and operations of the claimed subject matter.

#### BRIEF DESCRIPTION OF THE DRAWINGS

**[0009]** FIG. 1 schematically depicts a cross-sectional diagram of a multilayered stack undergoing laser processing, according to one or more embodiments shown and described herein.

#### DETAILED DESCRIPTION

**[0010]** Reference will now be made in detail to embodiments of apparatuses and methods for laser processing materials, examples of which are illustrated in the accompanying drawings. Whenever possible, the same reference numerals will be used throughout the drawings to refer to the same or like parts. One embodiment of a multilayered stack for laser processing is schematically depicted in FIG. 1. Generally, the laser processing may perforate a material that is transparent to the laser, sometimes referred to herein as the "transparent material," and the perforation may cause or contribute to cutting the transparent material at the perforation. The multilayered stack generally includes a transparent material which can be perforated or otherwise mechanically deformed by a laser beam incident on the top surface of the transparent material. The transparent material is positioned on a carrier, where at least a portion of the carrier is non-transparent to the laser beam. The carrier generally includes a support base and a laser disruption element positioned between the support base and the transparent material. The support base supports the transparent material and may be utilized to transport the transparent material to be laser processed. In one embodiment, the support base material may be non-transparent to the laser beam and may be damaged if contacted by a portion of a laser beam having an intensity great enough to damage the carrier, such as a focused area of a laser beam. However, the laser disruption element positioned between the transparent material and the support base may disrupt and diffuse a laser beam exiting the transparent material before it can contact the support base, such that upon optical disruption of the laser beam by the laser disruption element, the laser beam does not have sufficient intensity below the laser disruption element to damage the support base. As such, the laser disruption element may act as a shield to protect the support base from damage associated with contact with a portion of a laser beam with sufficient intensity to damage

the support base. Various embodiments of methods and apparatuses for use in laser processing transparent materials will be described herein with specific references to the appended claims.

**[0011]** Referring to FIG. 1, a multilayer stack 100 is schematically depicted. Generally, the multilayer stack 100 comprises a transparent material 160 and a carrier 110 which comprises a laser disruption element 140 and a support base 120. In embodiments described herein, the transparent material 160 is positioned on top of the laser disruption element 140, which is positioned on top of the support base 120. As used herein, reference to a position above or on top of another position assumes that the top or uppermost position is the surface of the multilayer stack 100 upon which the laser beam 180 is first incident. For example, in FIG. 1, the surface of the transparent material 160 that is closest to the source laser 188 is the top surface 162 and placement of the laser disruption element 140 below the transparent material 160 means that the laser beam 180 traverses the transparent material 160 before interacting with the laser disruption element 140. As shown in FIG. 1, the source laser 188 is transmitted through an optical element 184 which forms a focused area of the laser beam 180, such as a focal line 182, which is incident upon the transparent material 160.

**[0012]** The transparent material 160 may be laser processed with a laser beam 180 which may alone, or with other manufacturing steps, be utilized to cut the transparent material 160. As used herein, laser processing refers to cutting, perforating, ablating, or otherwise altering the mechanical integrity of a material with a laser beam 180. Generally, the laser beam 180 must have a certain intensity at a particular area of the transparent material 160 to alter the mechanical integrity of the transparent material 160. As such, a defocused or disrupted laser beam may not have sufficient intensity to mechanically affect a material at a selected area while a focused laser beam may have sufficient intensity to cut, perforate, or ablate an area of a laser processed material. However, a focused area of a laser beam, such as a laser beam with a focused focal line 182, may have sufficient intensity to perforate the transparent material 160 as well as to damage a support base 120 directly contacted by the focal line 182. A focal line 182 of a laser beam 180 may be produced by an optical assembly 184 which can optically alter the path of a source laser 188. Also, as used herein, in the context of laser beams, "intensity" may be referred to as "energy density" and the two terms are interchangeable. The laser beam 180 has a wavelength, and as used herein, a material that is "transparent" is substantially transparent to electromagnetic radiation of the wavelength of the laser such that the absorption by the transparent material 160 is less than about 10%, less than about 5%, or even less than about 1% per mm of material depth

at the wavelength of the laser. "Electromagnetic radiation" may be referred to herein as "light" and the two terms are interchangeable and may correspond with electromagnetic radiation both inside and outside of the visible spectrum.

**[0013]** The support base 120 is generally any structure capable of supporting the transparent material 160 which will be laser processed by the laser beam 180. The support base 120 may act as a carrying tray for the transparent material 160 and may have a substantially flat top surface 122, for interaction with a flat transparent material 160, and a substantially flat bottom surface 124, for interaction with a substantially flat work table upon which the support base 120 may be positioned. The support base 120 may be positioned on a table or other workspace for stability during laser processing. In one embodiment, the support base 120 may comprise aluminum. For example, the support base 120 may comprise greater than about 50%, greater than about 70%, greater than about 90%, greater than about 95%, or even greater than about 99% aluminum. In one embodiment, the support base 120 may comprise a honeycomb aluminum structure, such as ALUCORE®, commercially available from 3A Composites International AG. In another embodiment, the support base 120 may comprise polyoxymethylene. If non-transparent materials, such as the materials of the support base 120, are contacted by the focal line 182, the support base 120 can be damaged, which may result in contamination of the laser processed transparent material 160. As used herein, damage to the support base 120 includes, without limitation scratching, ablating, cutting, slashing, abrasion, scoring, or other disruption in the mechanical integrity of the top surface 122 of the support base 120.

**[0014]** In one embodiment, the support base 120 may be placed on a table or other workstation during the laser processing. The table or workstation may have a vacuum system which creates suction upon the surface of the table or workstation. For example, the table or workstation may have vacuum holes in its surface, and the support base 120 and laser disruption element 140 may have corresponding holes through which the vacuum may create suction and secure materials positioned on top of the laser disruption element 140. For example, the transparent material 160 may be secured to the disruption element 140 by vacuum suction which permeates through holes in the disruption element 140, support base 120, and workstation. The support base 120 and the laser disruption element 140 may be mechanically fastened to one another such as with screws, fasteners, pins, or other suitable means. As such, the transparent

material 160 can rest upon the laser disruption element 140 and be secured by the vacuum system while laser processed.

**[0015]** The transparent material 160 may be any material substantially transparent to the electromagnetic radiation of the laser beam 180. For example, the transparent material 160 may be, without limitation, glass, sapphire, silicon, silicon-carbide, quartz, alumina ( $Al_2O_3$ ), aluminum nitride (AlN), Zirconia ( $ZrO_2$ ), gallium-Nitride, gallium-arsenide (GaAs), gallium-phosphide (GaP), gallium-antimonide (GaSb), indium-arsenide (InAs), indium-phosphide (InP), indium-antimonide (InSb), cadmium-sulphide (CdS), cadmium-selenide (CdSe), cadmium-telluride (CdTe), zinc-sulfide (ZnS), zinc-selenide (ZnSe), zinc-telluride (ZnTe), germanium (Ge), lithium-niobate ( $LiNbO_3$ ), lithium-tantalate ( $LiTaO_3$ ), or combinations thereof. The transparent material 160 may have a substantially flat top surface 162 and a substantially flat bottom surface 164, such as would be suitable for cover glass for an electronic device. The top surface 162 and/or the bottom surface 164 may be polished. In another embodiment, the transparent material 160 may be a wafer material for semiconductor manufacturing. If glass is utilized as the transparent material 160, the glass may generally be any glass suitable for formation as a sheet. In some embodiments, the glass may be ion-exchangeable aluminosilicate glass. Examples of such ion-exchangeable aluminosilicate glass include, but are not limited to, Gorilla Glass® and Gorilla Glass II® (commercially available from Corning, Inc.). Such glass, especially after laser processing, may be well suited for many uses, such as, for example, as cover glass for hand-held consumer electronic devices.

**[0016]** The laser beam 180 may be operable to create small (micron and smaller) "holes" in the transparent material 160 for the purpose of drilling, cutting, separating, perforating, or otherwise processing the transparent material 160 at the focal line 182. More particularly, an ultrashort (i.e., from  $10^{-10}$  to  $10^{-15}$  second) pulse laser beam 180 having wavelengths such as 1064 nm, 532 nm, 355 nm, or 266 nm is focused, as the focal line 182, to an energy density above the threshold needed to create a defect in the region of focus at the surface of or within the transparent material 160. The laser beam 180 may have a repetition rate in a range of between about 1 kHz and 2 MHz, or in another embodiment, between about 10kHz and about 650kHz. By repeating the process, a series of laser-induced defects aligned along a predetermined path can be created in the transparent material 160. By spacing the laser-induced features sufficiently

close together, a controlled region of mechanical weakness within the transparent material 160 can be created and the transparent material 160 can be precisely fractured or separated (mechanically or thermally) along the path defined by the series of laser-induced defects (shown in FIG. 1 as the area of the transparent material 160 proximate the focal line 182). The ultrashort laser pulse(s) may be optionally followed by a carbon dioxide (CO<sub>2</sub>) laser or other source of thermal stress to effect fully automated separation of the transparent material 160. Representative laser beam 180 characteristics, which can be applied to laser process a transparent substrate, are described in detail in U.S. Patent Application 61917092 TITLED "METHOD AND DEVICE FOR THE LASER-BASED MACHINING OF SHEET-LIKE SUBSTRATES, the teachings of which are incorporated herein by reference in their entirety.

[0017] The wavelength of the laser beam 180 may be selected so that the material to be laser processed (drilled, cut, ablated, damaged or otherwise appreciably modified by the laser) is transparent to the wavelength of the laser. The selection of the laser source may also depend on the ability to induce multi-photon absorption (MPA) in the transparent material 160. MPA is the simultaneous absorption of multiple photons of identical or different frequencies in order to excite a material from a lower energy state (usually the ground state) to a higher energy state (excited state). The excited state may be an excited electronic state or an ionized state. The energy difference between the higher and lower energy states of the material is equal to the sum of the energies of the two photons. MPA is a third-order nonlinear process that is several orders of magnitude weaker than linear absorption. It differs from linear absorption in that the strength of absorption depends on the square of the light intensity, thus making it a nonlinear optical process. At ordinary light intensities, MPA is negligible. If the light intensity (energy density) is extremely high, such as in the region of the focal line 182 of a laser beam 180 (particularly a pulsed laser source), MPA becomes appreciable and leads to measurable effects in the material within the region where the energy density of the laser beam 180 is sufficiently high (i.e. the focal line 182). Within the region of the focal line 182, the energy density may be sufficiently high to result in ionization.

[0018] At the atomic level, the ionization of individual atoms has discrete energy requirements. Several elements commonly used in glass (e.g., Si, Na, K) have relatively low ionization energies, such as about 5 eV. Without the phenomenon of MPA, a laser wavelength



of about 248 nm would be required to create linear ionization at about 5 eV. With MPA, ionization or excitation between states separated in energy by about 5 eV can be accomplished with wavelengths longer than 248 nm. For example, photons with a wavelength of 532 nm have an energy of about 2.33 eV, so two photons with wavelengths of 532 nm can induce a transition between states separated in energy by about 4.66 eV in two-photon absorption (TPA).

[0019] Thus, atoms and bonds may be selectively excited or ionized in the regions of the transparent material 160 where the energy density of the laser beam 180 is sufficiently high to induce nonlinear TPA of a laser wavelength having half the required excitation energy. MPA can result in a local reconfiguration and separation of the excited atoms or bonds from adjacent atoms or bonds. The resulting modification in the bonding or configuration can result in non-thermal ablation and removal of matter from the region of the material in which MPA occurs. This removal of matter creates a structural defect (e.g. a defect line or "perforation") that mechanically weakens the transparent material 160 and renders it more susceptible to cracking or fracturing upon application of mechanical or thermal stress. By controlling the placement of perforations, a contour or path along which cracking occurs can be precisely defined and precise micromachining of the material can be accomplished. The contour defined by a series of perforations may be regarded as a fault line and corresponds to a region of structural weakness in the transparent material 160. In one embodiment, laser processing includes separation of a part from the transparent material 160 processed by the laser beam 180, where the part has a precisely defined shape or perimeter determined by a closed contour of perforations formed through MPA effects induced by the laser. As used herein, the term closed contour refers to a perforation path formed by the laser line, where the path intersects with itself at some location. An internal contour is a path formed where the resulting shape is entirely surrounded by an outer portion of material.

[0020] According to some embodiments perforations can be accomplished with the use of an ultra-short pulse laser in combination with optics that generates a focal line to fully perforate the body of a range of glass compositions. In some embodiments, the pulses are single pulses (i.e., the laser provides equally separated single pulses rather than pulse bursts (closely spaced single pulses that are grouped together), with the pulse duration of the individual pulses is in a range of between greater than about 1 picoseconds and less than about 100 picoseconds, such as greater than about 5 picoseconds and less than about 20 picoseconds, and the repetition rate of the individual pulses can be in a range of between about 1 kHz and 4 MHz, such as in a range of between about 10 kHz and

650 kHz. Perforations can also be accomplished with a single "burst" of high energy short duration pulses spaced close together in time. Such pulses can be produced in bursts of two pulses, or more (such as, for example, 3 pulses, 4, pulses, 5 pulses, 10 pulses, 15 pulses, 20 pulses, or more) separated by a duration between the individual pulses within the burst that is in a range of between about 1 nsec and about 50 nsec, for example, 10 to 30 nsec, such as about 20 nsec, and the burst repetition frequency can be in a range of between about 1 kHz and about 200 kHz. (Bursting or producing pulse bursts is a type of laser operation where the emission of pulses is not in a uniform and steady stream but rather in tight clusters of pulses.) The pulse burst laser beam can have a wavelength selected such that the material is substantially transparent at this wavelength. The laser pulse duration may be  $10^{-10}$  s or less, or  $10^{-11}$  s or less, or  $10^{-12}$  s or less, or  $10^{-13}$  s or less. For example, the laser pulse duration may be between about 1 picosecond and about 100 picoseconds, or in another embodiment, between about 5 picoseconds and about 20 picoseconds. These "bursts" may be repeated at high repetition rates (e.g. kHz or MHz). The average laser power per burst measured (if burst pulses are utilized) at the material can be greater than 40 microJoules per mm thickness of material, for example between 40 microJoules/mm and 2500 microJoules/mm, or between 500 and 2250 microJoules/mm. For example, for one embodiment when using a 0.1 mm-0.2 mm thick glass one may use 200  $\mu$ J pulse bursts to cut and separate the glass, which gives an exemplary range of 1000-2000  $\mu$ J/mm. For example, for an exemplary 0.5-0.7mm thick glass, one may use 400-700  $\mu$ J pulse bursts to cut and separate the glass, which corresponds to an exemplary range of 570  $\mu$ J/mm (400  $\mu$ J/0.7mm) to 1400  $\mu$ J/mm (700  $\mu$ J/0.5mm). The perforations may be spaced apart and precisely positioned by controlling the velocity of a substrate or stack relative to the laser through control of the motion of the laser and/or the substrate or stack. In one embodiment, in a single pass, a laser can be used to create highly controlled full line perforation through the material, with extremely little (less than about 75  $\mu$ m, or even less than about 50  $\mu$ m) subsurface damage and debris generation. This is in contrast to the typical use of spot-focused laser to ablate material, where multiple passes are often necessary to completely perforate the glass thickness, large amounts of debris are formed from the ablation process, and more extensive sub-surface damage (less than about 100  $\mu$ m) and edge chipping occur. These perforations, defect regions, damage tracks, or defect lines are generally spaced from 1 to 25 microns apart (for example, 3-12 microns, or 5-20 microns). According to some embodiments the pulsed laser has laser power of 10W-150W and produces pulse bursts with at least 2 pulses per pulse burst. According to some embodiments the pulsed laser has laser power of 10W-100 W and produces pulse bursts with at least 2 - 25 pulses per pulse burst. According to some embodiments the pulsed laser has laser power of 25 W-60 W, and produces pulse bursts with at least 2 -25 pulses per burst and the periodicity between the defect lines is 2-20 microns, or 2 to 15 microns, or 2-10 microns.

The pulse burst laser beam can have a wavelength selected such that the material is substantially transparent at this wavelength. . According to some embodiments the pulsed has a pulse duration of less than 10 picoseconds. According to some embodiments the pulsed laser has a pulse repetition frequency of between 10 kHz and 1000 kHz.

**[0021]** Thus, it is possible to create a microscopic (i.e., less than about 1  $\mu\text{m}$ , less than 0.5  $\mu\text{m}$  (for example  $\leq 400\text{ nm}$ , or  $\leq 300\text{ nm}$ ) or even less than about 100 nm in diameter (e.g. 50 nm -100nm)) elongated "hole" (also called a perforation or a defect line) in a transparent material 160 using a single high energy burst pulse. These individual perforations can be created at rates of several hundred kilohertz (several hundred thousand perforations per second, for example). Thus, with relative motion between the source and the material these perforations can be placed adjacent to one another (spatial separation varying from sub-micron to several microns as desired). This spatial separation is selected in order to facilitate cutting. In some embodiments the defect line is a "through hole", which is a hole or an open channel that extends from the top to the bottom of the transparent material 160. Furthermore, the internal diameter of a defect line can be as large as the spot diameter of the laser beam focal line, for example. The laser beam focal line can have an average spot diameter in a range of between about 0.1 micron and about 5 microns, for example 1.5 to 3.5 microns.

**[0022]** To form a focal line 182, a source laser 188 may be transmitted through an optical assembly 184. Suitable optical assemblies, which can optical assemblies can be applied, are described in detail in U.S. Patent Application No. 61917092 · TITLED "STACKED TRANSPARENT MATERIAL CUTTING WITH ULTRAFast LASER BEAM OPTICS, DISRUPTIVE LAYERS AND OTHER LAYERS, the teachings of which are incorporated herein by reference in their entirety. For example, an optical assembly 184 positioned in the beam path of the source laser 188 is configured to transform the source laser 188 into a focal line 182, viewed along the beam propagation direction, the laser beam focal line 182 having a length in a range of between 0.1 mm and 100 mm, for example, 0.1 to 10mm. The laser beam focal line can have a length in a range of between about 0.1 mm and about 10 mm, or between about 0.5 mm and about 5 mm, such as about 1 mm, about 2 mm, about 3 mm, about 4 mm, about 5 mm, about 6 mm, about 7 mm, about 8 mm, or about 9 mm, or a length in a range of between about 0.1 mm and about 1 mm, and an average spot diameter in a range of between about 0.1 micron and about 5

microns. The holes or defect lines each can have a diameter between 0.1 microns and 10 microns, for example 0.25 to 5 microns (e.g., 0.2-0.75 microns). For example, as shown in FIG. 1, a spherical or disc shaped optical assembly 184 may be utilized to focus the source laser 188 and form a focal line 182 of a defined length.

[0023] Note that typical operation of such a picosecond laser described herein creates a "burst" 500 of pulses 500A. Each "burst" (also referred to herein as a "pulse burst" 500) contains multiple individual pulses 500A (such as at least 2 pulses, at least 3 pulses, at least 4 pulses, at least 5 pulses, at least 10 pulses, at least 15 pulses, at least 20 pulses, or more) of very short duration. That is, a pulse burst is a "pocket" of pulses, and the bursts are separated from one another by a longer duration than the separation of individual adjacent pulses within each burst. Pulses 500A have pulse duration  $T_d$  of up to 100 psec (for example, 0.1 psec, 5 psec, 10 psec, 15 psec, 18 psec, 20 psec, 22 psec, 25 psec, 30 psec, 50 psec, 75 psec, or therebetween). The energy or intensity of each individual pulse 500A within the burst may not be equal to that of other pulses within the burst, and the intensity distribution of the multiple pulses within a burst 500 often follows an exponential decay in time governed by the laser design. Preferably, each pulse 500A within the burst 500 of the exemplary embodiments described herein is separated in time from the subsequent pulse in the burst by a duration  $T_p$  from 1 nsec to 50 nsec (e.g. 10-50 nsec, or 10-30 nsec, with the time often governed by the laser cavity design). For a given laser, the time separation  $T_p$  between adjacent pulses (pulse -to- pulse separation) within a burst 500 is relatively uniform ( $\pm 10\%$ ). For example, in some embodiments, each pulse within a burst is separated in time from the subsequent pulse by approximately 20 nsec (50 MHz). For example, for a laser that produces pulse separation  $T_p$  of about 20 nsec, the pulse to pulse separation  $T_p$  within a burst is maintained within about  $\pm 10\%$ , or about  $\pm 2$  nsec. The time between each "burst" of pulses (i.e., time separation  $T_b$  between bursts) will be much longer (e.g.,  $0.25 \leq T_b \leq 1000$  microseconds, for example 1-10 microseconds, or 3-8 microseconds). In some of the exemplary embodiments of the laser described herein the time separation  $T_b$  is around 5 microseconds for a laser with burst repetition rate or frequency of about 200 kHz. The laser burst repetition rate is relates to the time  $T_b$  between the first pulse in a burst to the first pulse in the subsequent burst (laser burst repetition rate =  $1/T_b$ ). In some embodiments, the laser burst repetition frequency may be in a range of between about 1 kHz and about 4 MHz. More preferably, the laser burst repetition rates can be, for example, in a range of between about 10 kHz and 650 kHz. The time  $T_b$  between the first pulse in each burst to the first pulse in the subsequent burst may be 0.25 microsecond (4 MHz burst repetition rate) to 1000 microseconds (1 kHz burst

repetition rate), for example 0.5 microseconds (2 MHz burst repetition rate) to 40 microseconds (25 kHz burst repetition rate), or 2 microseconds (500 kHz burst repetition rate) to 20 microseconds (50k Hz burst repetition rate). The exact timings, pulse durations, and burst repetition rates can vary depending on the laser design, but short pulses ( $T_d < 20$  psec and preferably  $T_d \leq 15$  psec) of high intensity have been shown to work particularly well.

**[0024]** The energy required to modify or perforate the material (e.g., glass) can be described in terms of the burst energy - the energy contained within a burst (each burst 500 contains a series of pulses 500A), or in terms of the energy contained within a single laser pulse (many of which may comprise a burst). For these applications, the energy per burst can be from 25-750  $\mu\text{J}$ , more preferably 50-500  $\mu\text{J}$ , or 50-250  $\mu\text{J}$ . In some embodiments the energy per burst is 100-250  $\mu\text{J}$ . The energy of an individual pulse within the pulse burst will be less, and the exact individual laser pulse energy will depend on the number of pulses 500A within the pulse burst 500 and the rate of decay (e.g., exponential decay rate) of the laser. For example, for a constant energy/burst, if a pulse burst contains 10 individual laser pulses 500A, then each individual laser pulse 500A will contain less energy than if the same pulse burst 500 had only 2 individual laser pulses.

**[0025]** Laser "ablative" cutting of thin glasses, as described in some embodiments herein, has advantages that include no minimization or prevention of crack creation at or near the region of ablation and the ability to perform free form cuts of arbitrary shape. It is beneficial to avoid edge cracking and residual edge stress in glass substrates for flat panel displays because flat panel displays have a pronounced propensity to break from an edge, even when stress is applied to the center. The high peak power of ultrafast lasers combined with tailored beam delivery in the method described herein can avoid these problems because the present method is a "cold" ablation technique that cuts without a deleterious heat effect. Laser cutting by ultrafast lasers according to the present method produces essentially no residual stress in the glass. However, it should be understood that any type of laser may be utilized in the laser processing methods and apparatus described herein.

**[0026]** Still referring to FIG. 1, positioned on top of the support base 120 and between the support base 120 and the transparent material 160 is the laser disruption element 140. In one embodiment, the laser disruption element 140 may be a substantially flat sheet with a substantially flat top surface 142 and bottom surface 144 which correspond with the flat surface of the top surface 122 of the support base 120 and the bottom surface 164 of the transparent material 160, respectively. Generally, the laser disruption element 140 optically

disrupts a laser beam 180 transmitted through the transparent material 160 such that the laser beam 180 does not have sufficient intensity (i.e., at the focal line 182) below the laser disruption element 140 to damage the support base 120. For example, optical disruption may include reflection, absorption, scattering, defocusing or otherwise interfering with the laser beam 180. The disruption element 140 may reflect, absorb, scatter, defocus or otherwise interfere with an incident laser beam 180 to inhibit or prevent the laser beam 180 from damaging or otherwise modifying underlying layers in the multilayer stack 100, such as the support base 120.

[0027] In one embodiment, the laser disruption element 140 is positioned immediately below the transparent material 160 which is laser processed. Such a configuration is shown in FIG. 1, where the beam disruption element 140 is a substantially flat sheet positioned immediately below the transparent material 160 in which the laser processing described herein will occur. In some embodiments, the laser disruption element 140 may be positioned in direct contact with the support base 120, but in other embodiments another layer of material may be disposed between the support base 120 and the laser disruption element 140. In one embodiment, the laser disruption element 140 may have a thickness as measured from its top surface 142 to its bottom surface 144 from about 0.5 mm to about 3 mm. The edges of the laser disruption element 140 may have a rounded shape with beveled comers, substantially free of sharp comers.

[0028] The laser disruption element 140 has different optical properties than the transparent material 160 to be cut by laser processing. For example, the beam disruption element 140 may comprise a defocusing element, a scattering element, a translucent element, or a reflective element. A defocusing element is an interface or a layer comprising a material that prevents the laser beam light 180 from forming the laser beam focal line 182 on or below the defocusing element. The defocusing element may comprise a material or interface with refractive index inhomogeneities that scatter or perturb the wavefront of the laser beam 180. In embodiments where the laser disruption element is a translucent element, the translucent element is an interface or layer of material that allows light to pass through, but only after scattering or attenuating the laser beam 180 to lower the energy density sufficiently to prevent formation of a laser beam focal line 182 in portions of the multilayer stack 100 on the side of the translucent element that are opposite from the laser beam 180.

**[0029]** As shown in FIG. 1, a laser beam 180 may pass into and through the transparent material 160 and contact the top surface 142 of the laser disruption element 140. The laser disruption element 140 may disrupt the laser beam 180 such that the intensity of the laser beam 180 is reduced before it reaches the support base 120. More specifically, the reflectivity, absorptivity, defocusing, attenuation, and/or scattering of the disruption element 140 can be utilized to create a barrier or impediment to the laser radiation. It is not necessary that the absorption, reflection scattering, attenuation, defocusing etc. of the laser beam 180 by the disruption element 140 be complete. The effect of the disruption element 140 on the laser beam 180 may be sufficient to reduce the energy density or intensity of the focal line 182 to a level below the threshold required for cutting, ablation, perforating etc. of the support base 120. In one embodiment, the disruption element 140 reduces the energy density or intensity of the focal line 182 to a level below the threshold needed to damage the support base 120. The laser disruption element 140 may be a layer or an interface and may be configured to absorb, reflect, or scatter the laser beam 180, where the absorption, reflection, or scattering are sufficient to reduce the energy density or intensity of the laser beam 180 transmitted to the support base 120 (or other underlying layer) to a level below that required to cause damage to the support base 120 or other underlying layers.

**[0028]** In one embodiment, the laser disruption element 140 may optically disrupt the laser beam 180 at the top surface 142 of the laser disruption element 140. For example, in one embodiment, the laser disruption element 140 may comprise a film on its top layer 142 or a surface modified top surface 142. For example, the disruption element 140 may comprise a roughened top surface 142 (surface nearest the transparent material 160) which is modified to be substantially rough to scatter incident light. Additionally, if the top surface 142 of the laser disruption element 140 acts to interfere with the laser beam 180, the bulk material of the laser disruption layer may be substantially the same material as the transparent substrate since no focal line 182 is formed below the top surface 142 of the laser disruption element 140. For example, in one embodiment, the transparent material 160 may be glass and the disruption element 140 may be glass. Furthermore, a laser disruption element 140 that has a bulk material transparent to the laser wavelength can transmit the laser and substantially disperse the intensity throughout the bulk material structure of the disruption element 140. In such an embodiment, the laser disruption element 140 is not damaged by a laser beam 180 transmitted through the transparent

material 160.

**[0029]** In one embodiment, the laser disruption element 140 may comprise frosted glass, such as, for example, a sheet of frosted glass. The frosted glass, sometimes referred to as iced glass, may be substantially translucent. The relatively rough top surface 142 may act as a translucent element which scatters an incident laser beam 180. The frosted glass may be chemically etched, sand blasted, or otherwise manufactured to have a translucent appearance that operates to disrupt incident light. However, in one embodiment, the frosted glass may be substantially smooth so as to not damage a transparent material 160 which is resting its top surface 142 during laser processing. For example, sand blasted frosted glass may be rough enough to damage a laser processed transparent material 160 by scratching when the transparent material 160 is placed on the laser disruption element 140. However, chemically etched glass may provide suitable optical characteristics while still being sufficiently smooth to not damage the transparent material 160.



As used herein, damage to the transparent material 160 means damage that is detectable by a human eye, such as scratches, cuts, or other abrasions.

[0030] In one embodiment, the average roughness (Ra) of the top surface 142 may be greater than or equal to about 0.5 microns, greater than or equal to about 0.8 microns, greater than or equal to about 1.0 microns, greater than or equal to about 1.5 microns, or even greater than or equal to about 2.0 microns, As used herein, Ra is defined as the arithmetic average of the differences between the local surface heights and the average surface height and can be described by the following equation:

$$R_a = \frac{1}{n} \sum_{i=1}^n |y_i|$$

where  $Y_i$  is the local surface height relative to the average surface height. In other embodiments Ra may be from about 0.5 microns to about 2.0 microns, from about 0.5 microns to about 1.5 microns, or from about 0.5 microns to about 1.0 micron. For example, in one embodiment, the frosted glass may be EagleEtch® acid etched glass commercially available from EuropTec USA of Clarksburg, WV.

[0031] In another embodiment, the laser disruption element 140 may comprise a surface film layer that acts to disrupt the laser beam 180 and substantially protect underlying layers such as the support base 120. The optically disrupting film layer may be deposited by thermal evaporation, physical vapor deposition, and/or sputtering, where the thickness may be a function of the wavelength of the utilized laser. The thin films may comprise, without limitation,  $MgF_2$ ,  $CaF_2$ , poly(methyl methacrylate), PMMA, polycarbonates, styrene-acrylonitrile copolymers, polystyrenes, cyclic olefin polymer, cyclic olefin copolymers, and combinations thereof.

[0032] It will be apparent to those skilled in the art that various modifications and variations can be made to the embodiments described herein without departing from the spirit and scope of the claimed subject matter. Thus it is intended that the specification cover the modifications and variations of the various embodiments described herein provided such modification and variations come within the scope of the appended claims and their equivalents.

## CLAIMS

What is claimed is:

1. A method of laser processing a transparent material, the method comprising:
  - positioning the transparent material on a carrier; and
  - transmitting a laser beam through the transparent material, the laser beam incident on a side of the transparent material opposite the carrier, wherein:
    - the transparent material is substantially transparent to the laser beam;
    - the carrier comprises a support base and a laser disruption element; and
    - the laser disruption element optically disrupts the laser beam transmitted through the transparent material such that the laser beam does not have sufficient intensity below the laser disruption element to damage the support base.
2. The method of claim 1, wherein the laser disruption element comprises frosted glass.
3. The method of claim 1 or 2, wherein at least a portion of the carrier is non-transparent to the laser beam.
4. The method of claim 1, 2, or 3, wherein the laser disruption element is not damaged by the laser beam transmitted through the transparent material.
5. The method of claim 1, wherein the transparent material is glass.
6. The method of claim 1, further comprising perforating the transparent material with the laser beam incident on the transparent material.
7. The method according to any of the preceding claims, wherein the laser beam has a pulse duration between about 1 picosecond and about 100 picoseconds.

8. The method according to any of the preceding claims, wherein the laser beam has a pulseburst repetition rate of between about 1kHz and 2 MHz and each pulse burst has at least two pulses.
9. The method according to any of the preceding claims, wherein the laser disruption element comprises a roughened surface that optically disrupts the laser beam.
10. The method of claim 9, wherein an average roughness (Ra) of the roughened surface is greater than or equal to about 0.5 microns.
11. The method of claim 9 or 10, wherein the roughened surface is the surface of the laser disruption element nearest the transparent material.
12. The method of any claim 1-8, wherein the laser disruption element is a substantially flat sheet.
13. The method of claim 1-8, or 12, wherein the laser disruption element is translucent.
14. A multilayer stack for laser processing, the multilayer stack comprising:
  - a carrier comprising a support base and a laser disruption element, the laser disruption element positioned on top of the support base; and
  - a transparent material positioned on the carrier, the transparent material comprising a substantially flat top surface and a substantially flat bottom surface, wherein the transparent material is substantially transparent to a laser beam incident on a surface of the transparent material opposite the carrier, wherein:
    - the laser disruption element optically disrupts the laser beam transmitted through the transparent material such that the laser beam does not have sufficient intensity below the laser disruption element to damage the support base.
15. The multilayer stack of claim 14, wherein the laser disruption element

comprises a roughened surface that optically disrupts the laser beam.

16. The multilayer stack of claim 15, wherein an average roughness (Ra) of the roughened surface is greater than or equal to about 0.5 microns.

17. A method of protecting a carrier when laser processing a transparent material positioned on the carrier, the method comprising:

positioning the transparent material on top of the carrier, the carrier comprising a support base;

transmitting a laser beam through the transparent material, wherein the laser beam is incident on a surface of the transparent material opposite the carrier, the laser beam comprising a focal area having an intensity sufficient to damage the carrier; and

positioning a laser disruption element between the support base and the transparent material, the laser disruption element optically disrupting the laser beam transmitted through the transparent material such that the laser beam does not have sufficient intensity at any point below the laser disruption element to damage the support base.

18. The method of claim 17, wherein the laser disruption element comprises a roughened surface that optically disrupts the laser beam.

19. The method of claim 18, wherein an average roughness (Ra) of the roughened surface is greater than or equal to about 0.5 microns.

20. The method of claim 17, wherein the laser disruption element comprises frosted glass.

21. The method of claim 1, wherein the laser beam is produced by pulsed laser and the pulsed laser has laser power of 10W-150W and produces pulse bursts with at least 2 pulses per pulse burst.

22. The method of claim 21, wherein the pulsed laser has laser power of 10W-100 W and produces pulse bursts with at least 2 - 25 pulses per pulse burst.

23. The method of claim 21, wherein the pulsed laser has laser power of 25 W-60 W, and produces pulse bursts with at least 2 -25 pulses per burst and the periodicity between the defect lines is 2-20

microns.

24. The method of claim 23 wherein the laser disruption element comprises frosted glass.
25. The method of claim 1 or 17, wherein the pulsed laser has laser power of 10W-150W and produces pulse bursts with at least 2 pulses per pulse burst.
26. The method of claim 25, wherein the pulsed laser has laser power of 10W-100 W and produces pulse bursts with at least 2 - 25 pulses per pulse burst.
27. The method of claim 25, wherein the pulsed laser has laser power of 25 W-60 W, and produces pulse bursts with at least 2 -25 pulses per burst and the periodicity between the defect lines is 2-20 microns.
28. The method of claim 1 or 17, wherein the laser beam is produced by pulsed laser.
29. The method of claim 28, wherein the pulsed laser has a pulse duration of between about 10 picoseconds and about 100 picoseconds.
30. The method of claim 29, wherein the pulsed laser has a pulse duration less than 10 picoseconds.
31. The method of claim 28, 29, or 30, wherein the pulsed laser has a pulse repetition frequency of between 10 kHz and 1000 kHz.

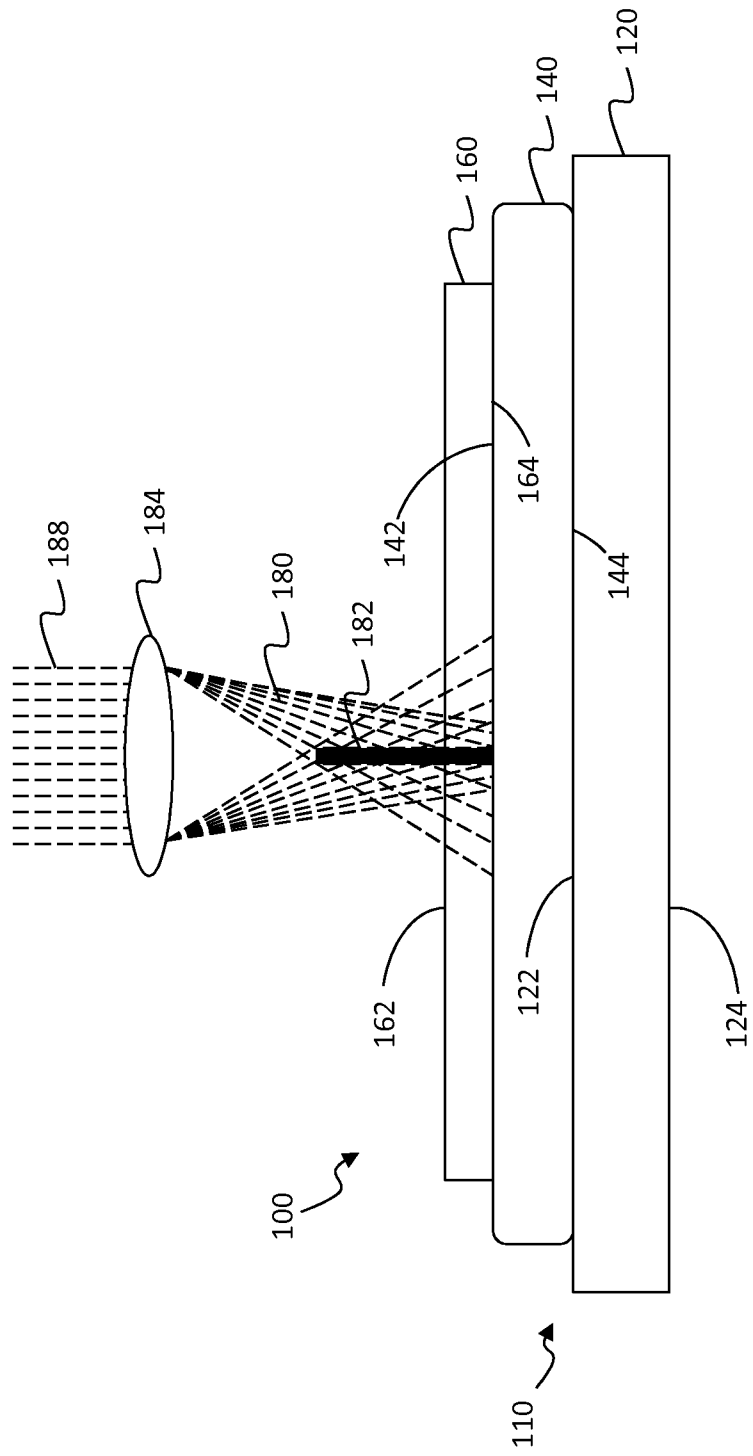


FIG. 1

**INTERNATIONAL SEARCH REPORT**

International application No  
PCT/US2015/039468

**A. CLASSIFICATION OF SUBJECT MATTER**  
 INV. C03B33/02 C03B33/09  
 ADD.  
 According to International Patent Classification (IPC) or to both national classification and IPC

**B. FIELDS SEARCHED**  
 Minimum documentation searched (classification system followed by classification symbols)  
 C03B B23K

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)  
 EPO-Internal

**C. DOCUMENTS CONSIDERED TO BE RELEVANT**

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2007/111480 A1 (MARUYAMA YUMI [JP] ET AL) 17 May 2007 (2007-05-17) paragraphs [0022], [0023], [0081] - [0085]; figures 1-4,8-10b -----	1-14, 16-31
X	EP 2 133 170 A1 (NITTO DENKO CORP [JP]) 16 December 2009 (2009-12-16) paragraphs [0050], [0051]; figures 1,4 -----	1-31
X	US 2013/189806 A1 (HOSHINO HITOSHI [JP]) 25 July 2013 (2013-07-25) paragraphs [0035], [0036]; figure all -----	1-31

Further documents are listed in the continuation of Box C.

See patent family annex.

\* Special categories of cited documents :

<p>"A" document defining the general state of the art which is not considered to be of particular relevance</p> <p>"E" earlier application or patent but published on or after the international filing date</p> <p>"L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)</p> <p>"O" document referring to an oral disclosure, use, exhibition or other means</p> <p>"P" document published prior to the international filing date but later than the priority date claimed</p>	<p>"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention</p> <p>"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone</p> <p>"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art</p> <p>"&amp;" document member of the same patent family</p>
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Date of the actual completion of the international search <b>9 October 2015</b>	Date of mailing of the international search report <b>19/10/2015</b>
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Name and mailing address of the ISA/ European Patent Office, P.B. 5818 Patentlaan 2 NL - 2280 HV Rijswijk Tel. (+31-70) 340-2040, Fax: (+31-70) 340-3016	Authorized officer <b>Marrec, Patrick</b>
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Information on patent family members

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